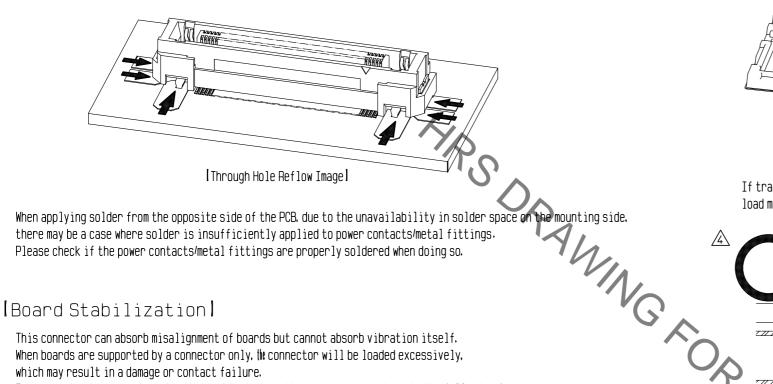


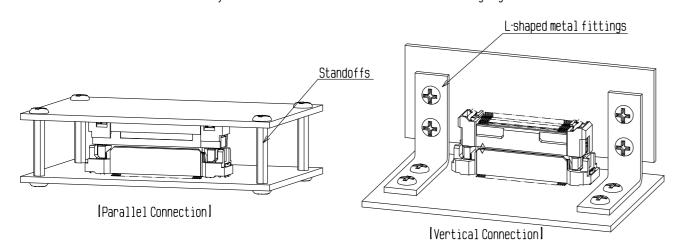
In order to prevent any potential failures with the connector, please read the following below:

Through Hole Reflow Process

FX23 and FX23L Series use through hole reflow process, where power contacts/metal fittings draw solder paste from the surrounding area. In regards to the soldering paste print area. the surface shall be flat with no exposed copper surface. If the surface is not flat, power contacts/metal fittings may not properly draw the soldering paste. resulting insufficient solder on the power contacts/metal fittings as well as ball-shaped solw on the PCB.



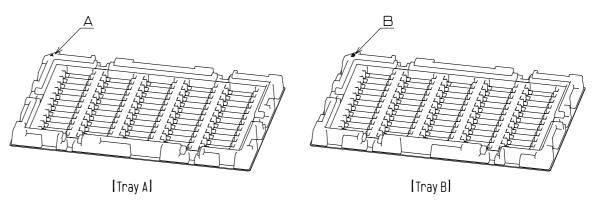
which may result in a damage or contact failure. Take measures to secure boards with an object other than connector as shown in the following figure.



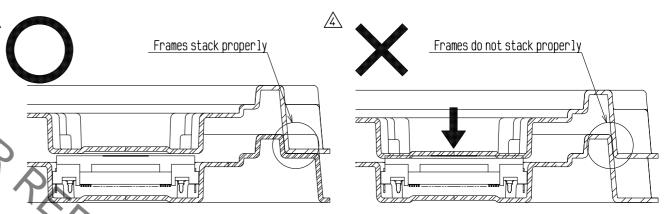
Note that when A spacer is installed far from connectors, incomplete mating of the connectors may occur due to sagging of the board, etc. Mate connectors surely and then fix a spacer.

When Storing with Tray Packaging

Please be cautious when stacking trays when storing. There are two types of trays (tray A, tray B), and designed to stack alternatingly.



If tray A is stacked to another tray A or tray B is stacked to another tray B. load may applied to the connector, causing the deformation or breakage of the connector.



If the tray is stacked correctly, tray's frame prevents from upper tray applying force to the conncetor

If same type of tray is stacked on top of eachother. load will be directly applied to the connector.

When storing, please stack the trays alternatively (tray A, tray B, tray A, tray B, tray A, tray B, tray A,...)

In Regards to Design Guideline

To provide more information in regards to the usage of this product, we have prepared a detailed manual (ETAD-F0887-00).

Please contact our sales representative if needed.

		DRAWING NO.	EDC-353556-00-00		
		PART NO.	FX23-120S-0.5SV		
		CODE NO.	CL573-3206-3-00	4	2/
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Added the second page.